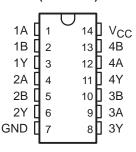
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- EPIC ™ (Enhanced-Performance Implanted **CMOS) Submicron Process**
- ESD Protection Exceeds 2000 V Per Mil-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)  $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)  $> 2 V at V_{CC} = 3.3 V, T_A = 25^{\circ}C$
- Inputs Accept Voltages to 5.5 V
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) **Packages**

#### D, DB, OR PW PACKAGE (TOP VIEW)



## description

This quadruple 2-input positive-AND gate is designed for 2.7-V to 3.6-V V<sub>CC</sub> operation.

The SN74LVC08 performs the Boolean functions  $Y = A \cdot B$  or  $Y = \overline{A + B}$  in positive logic.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-/5-V system environment.

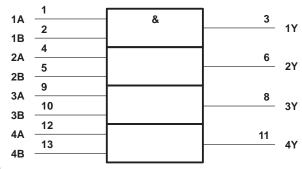
The SN74LVC08 is characterized for operation from -40°C to 85°C.

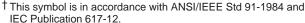
#### **FUNCTION TABLE** (each gate)

INP	JTS	OUTPUT
Α	В	Υ
Н	Н	Н
L	X	L
X	L	L

# logic symbol<sup>†</sup>

# logic diagram, each gate (positive logic)









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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$\ldots$ $-0.5\ V$ to 6.5 $V$
Input voltage range, V <sub>I</sub> (see Note 1)	$\dots$ $-0.5\ V$ to 6.5 $V$
Output voltage range, VO (see Notes 1 and 2) –	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	−50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	$\dots \dots  \pm 50 \text{ mA}$
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\dots \dots  \pm 50 \text{ mA}$
Continuous current through V <sub>CC</sub> or GND	$\dots \dots  \pm 100 \; mA$
Maximum power dissipation at $T_A = 55^{\circ}$ C (in still air) (see Note 3): D package	1.25 W
DB or PW package	0.5 W
Storage temperature range, T <sub>stg</sub>	$\dots$ -65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This value is limited to 4.6 V maximum.
  - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage	Operating	2	3.6	V
		Data retention only	1.5		
$V_{IH}$	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
V <sub>IL</sub>	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V
٧ <sub>I</sub>	Input voltage		0	5.5	V
٧o	Output voltage		0	VCC	V
1	High-level output current	V <sub>CC</sub> = 2.7 V		-12	mA
ЮН		V <sub>CC</sub> = 3 V		-24	IIIA
	Low lovel output output	V <sub>CC</sub> = 2.7 V		12	mA
IOL	Low-level output current	V <sub>CC</sub> = 3 V		24	IIIA
Δt/Δν	Input transition rise or fall rate		0	8	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	v <sub>cc</sub> †	MIN TYP‡	MAX	UNIT	
VOH	$I_{OH} = -100 \mu\text{A}$	MIN to MAX	V <sub>CC</sub> −0.2			
	10 m 4	2.7 V	2.2		V	
	IOH = -12  mA	3 V	2.4			
	$I_{OH} = -24 \text{ mA}$	3 V	2.2			
VOL	I <sub>OL</sub> = 100 μA	MIN to MAX		0.2	V	
	I <sub>OL</sub> = 12 mA	2.7 V		0.4		
	I <sub>OL</sub> = 24 mA	3 V		0.55		
ΙĮ	V <sub>I</sub> = 5.5 V or GND	3.6 V		±5	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		10	μΑ	
∆lCC	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V		500	μΑ	
Ci	$V_I = V_{CC}$ or GND	3.3 V	5		pF	

For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

# switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		UNIT
	(INFOT)		MIN	MAX	MIN	MAX	
<sup>t</sup> pd	A or B	Υ	1	6		7	ns
t <sub>sk(o)</sub> §				1			ns

<sup>§</sup> Skew between any two outputs of the same package switching in the same direction. This parameter is warranted but not production tested.

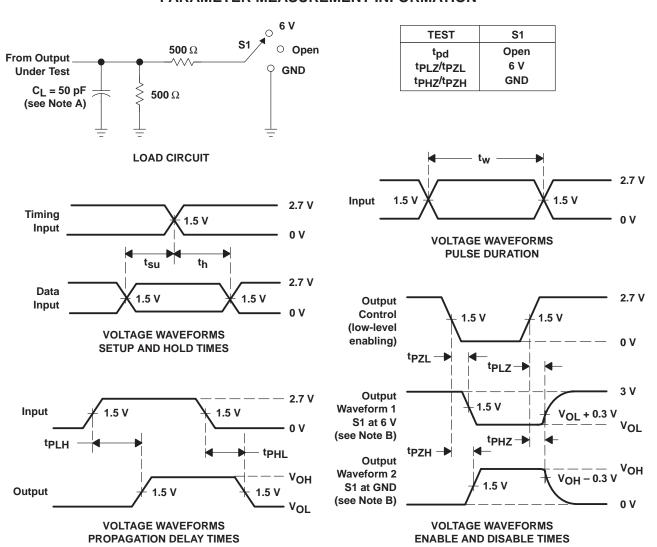
## operating characteristics, $V_{CC}$ = 3.3 V, $T_A$ = 25°C

	PARAMETER		TEST CONDITIONS		
C <sub>pd</sub>	Power dissipation capacitance per gate	C <sub>L</sub> = 50 pF,	f = 10 MHz	10	pF



<sup>‡</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2.5$  ns,  $t_f \leq 2.5$  ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpz and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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